

Title (en)  
OFFSET COMPENSATION METHOD

Title (de)  
VERFAHREN ZUR VERSATZMASSKOMPENSATION

Title (fr)  
PROCÉDÉ DE COMPENSATION DE COTE DE DÉALIGNEMENT

Publication  
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Application  
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Abstract (en)  
[origin: WO2020201245A1] The invention relates to a method for detecting and compensating for a degree of offset between the punching coordinates of a punching device and the laser coordinates of a laser device when using a combination punch-laser machine for machining a plate-shaped workpiece, in particular sheet metal. The method has the following steps: a. introducing a structure into the plate-shaped workpiece by means of the punching device or by means of the laser device; b. ascertaining a measurement variable of the structure which is introduced using the laser device or using the punching device; c. comparing the measurement variable with an expected variable, wherein a deviation between the measurement variable and the expected variable corresponds to a degree of offset; and d. calculating the degree of offset using the coordinates of the laser device in the laser coordinate system or the coordinates of the punching device in the punching coordinate system in order to compensate for the degree of offset between the punching coordinates and the laser coordinates.

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